

FEATURES

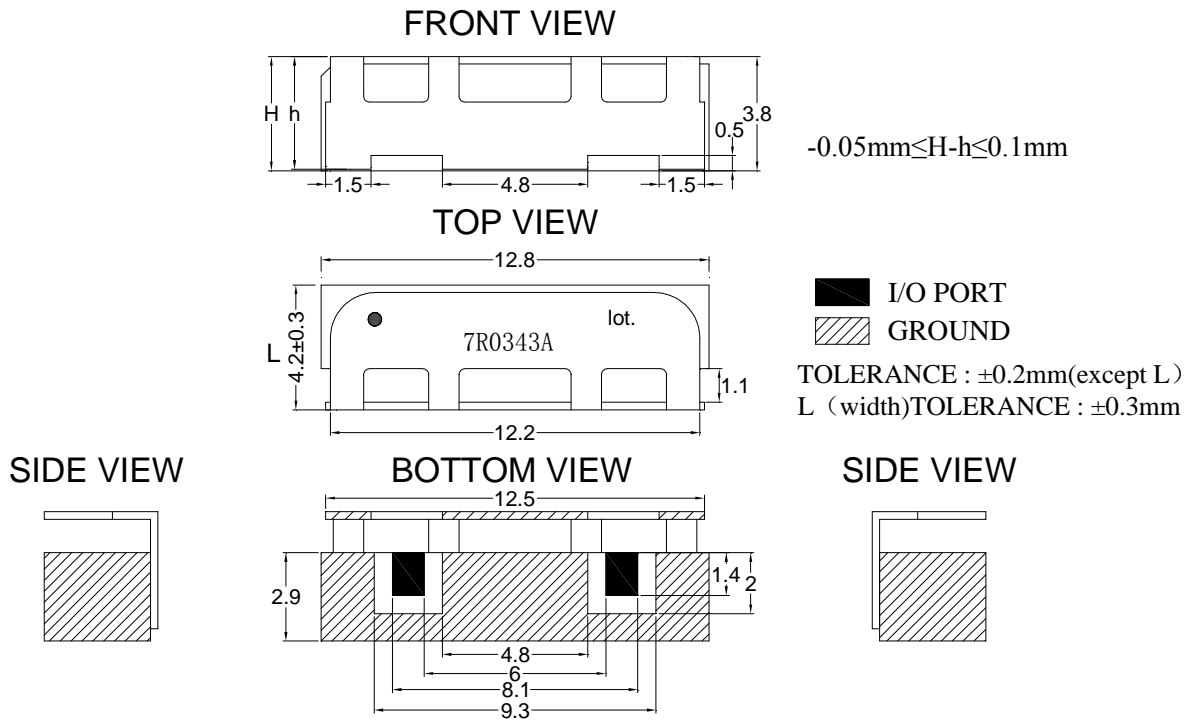
- Small Size,Light weight
- SMT package soldering
- Ideal for Microwave telecommunication

SPECIFICATIONS

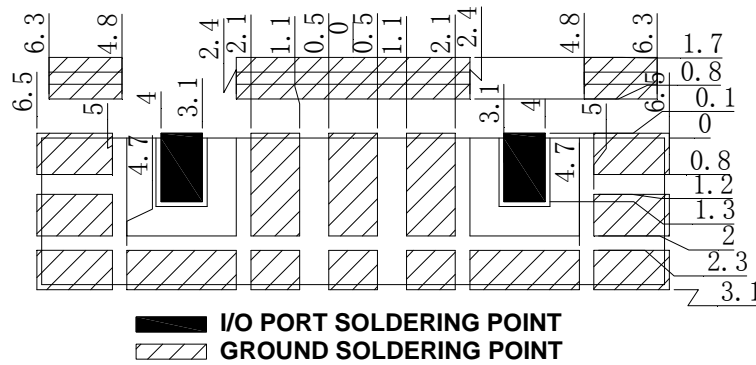
NO.	ITEM	Spec			UNIT	
		Min	Typ	Max		
1	Center Frequency	5935	6530	7125	MHz	
2	Bandwidth [BW]	/	1190	/	MHz	
3	Insertion Loss @5935~5945MHz	/	3.3	3.5	dB	
	Insertion Loss @5945~7125MHz	/	/	3.0		
4	Ripple in BW (any 320MHz)	/	/	2.3	dB	
5	VSWR in BW	/	/	2.0	/	
6	Attenuation [Absolute Value]	@30~2500MHz	35	/	/	dB
		@2512~3600MHz	30	/	/	
		@3800~4200MHz	30	/	/	
		@4800~4900MHz	30	/	/	
		@5170~5490MHz	50	/	/	
		@5490~5835MHz	45	49	/	

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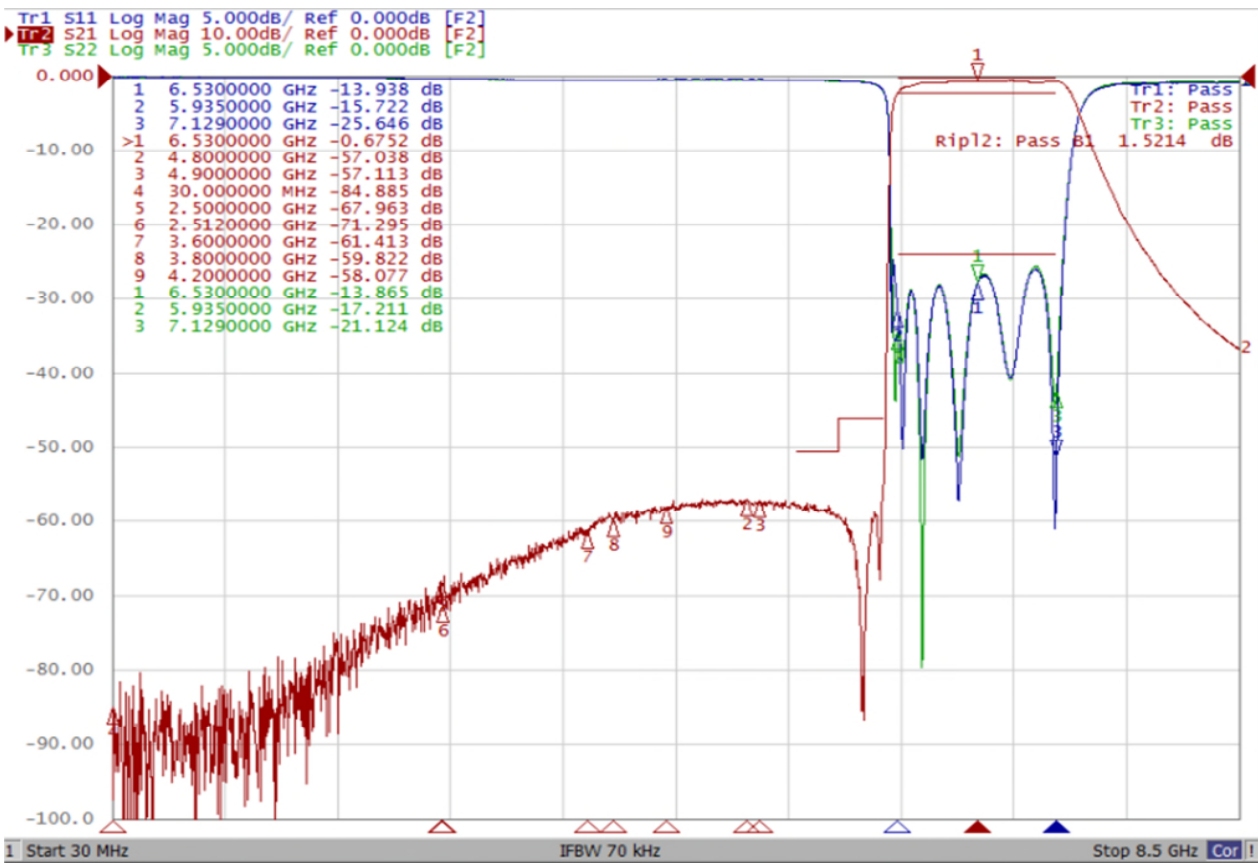
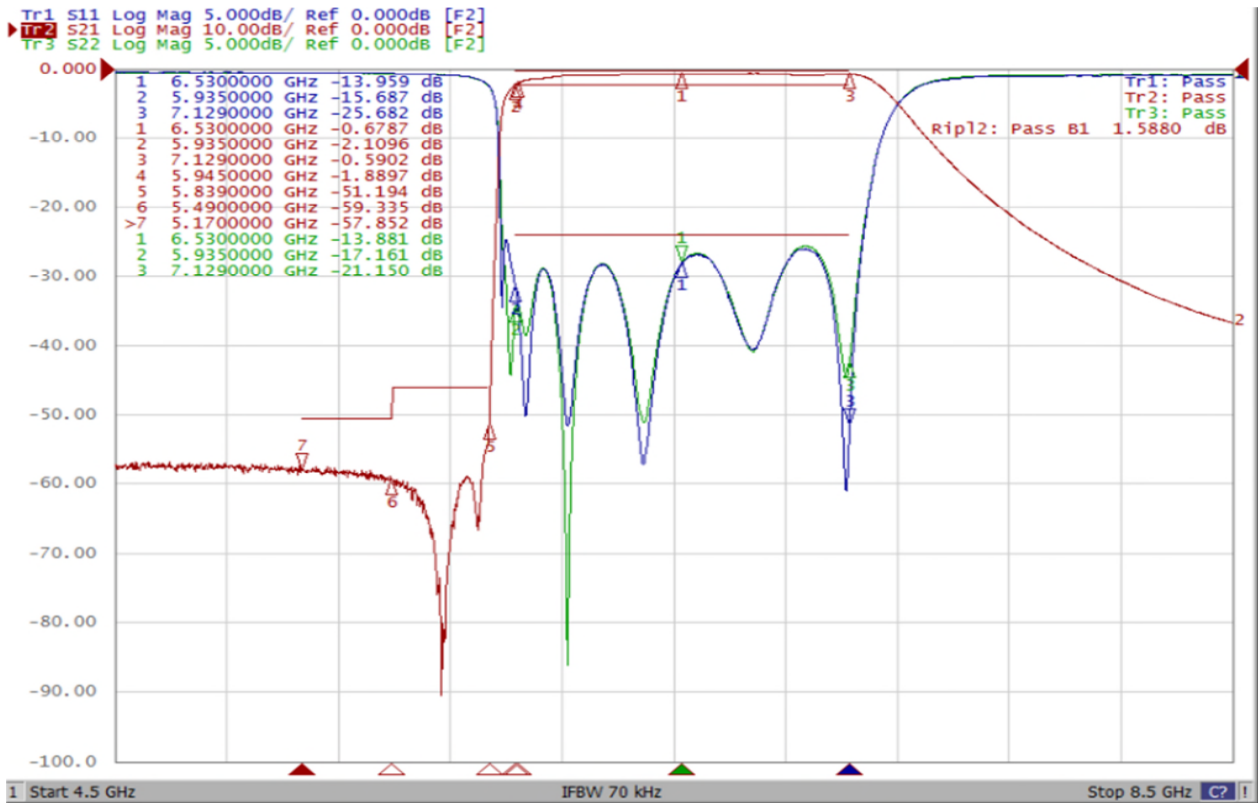
OUTLINE DRAWING



FOOTPRINT



ELECTRICAL CHARACTERISTICS CURVE



ABSOLUTE MAXIMUM RATINGS

Operation Temperature	-40°C to +95°C
Storage Temperature	-40°C to +95°C
Max. Input Power	33dBm

NOTES

- RoHS 2.0/HSF
- Reflow soldering temperature curve

